

SN54BCT2240, SN74BCT2240 OCTAL BUFFERS AND LINE/MOS DRIVERS WITH 3-STATE OUTPUTS

SCBS030E – SEPTEMBER 1988 – REVISED MARCH 2003

- Operating Voltage Range of 4.5 V to 5.5 V
- State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}
- Output Ports Have Equivalent 33- Ω Series Resistors, So No External Resistors Are Required
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers

description/ordering information

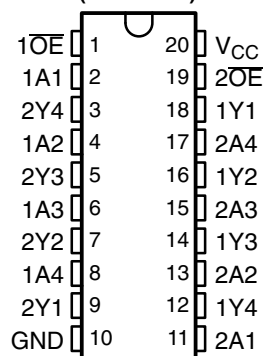
These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the SN74BCT2241 and the 'BCT2244 devices, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable ($\overline{OE}$) inputs, and complementary OE and $\overline{OE}$ inputs. These devices feature high fan-out and improved fan-in.

The 'BCT2240 devices are organized as two 4-bit line drivers with separate output-enable ($\overline{OE}$) inputs. When $\overline{OE}$ is low, the device passes data from the A inputs to the Y outputs. When $\overline{OE}$ is high, the outputs are in the high-impedance state.

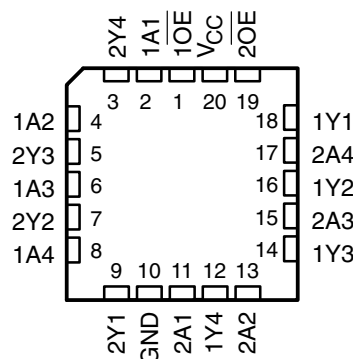
To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The outputs, which are designed to source or sink up to 12 mA, include 33- Ω series resistors to reduce overshoot and undershoot.

SN54BCT2240 . . . J OR W PACKAGE
SN74BCT2240 . . . DB, DW, N, OR NS PACKAGE
(TOP VIEW)



SN54BCT2240 . . . FK PACKAGE
(TOP VIEW)



ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74BCT2240N	SN74BCT2240N
	SOIC – DW	Tube	SN74BCT2240DW	BCT2240
		Tape and reel	SN74BCT2240DWR	
	SOP – NS	Tape and reel	SN74BCT2240NSR	BCT2240
–55°C to 125°C	SSOP – DB	Tape and reel	SN74BCT2240DBR	BA240
	CDIP – J	Tube	SNJ54BCT2240J	SNJ54BCT2240J
	CFP – W	Tube	SNJ54BCT2240W	SNJ54BCT2240W
	LCCC – FK	Tube	SNJ54BCT2240FK	SNJ54BCT2240FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

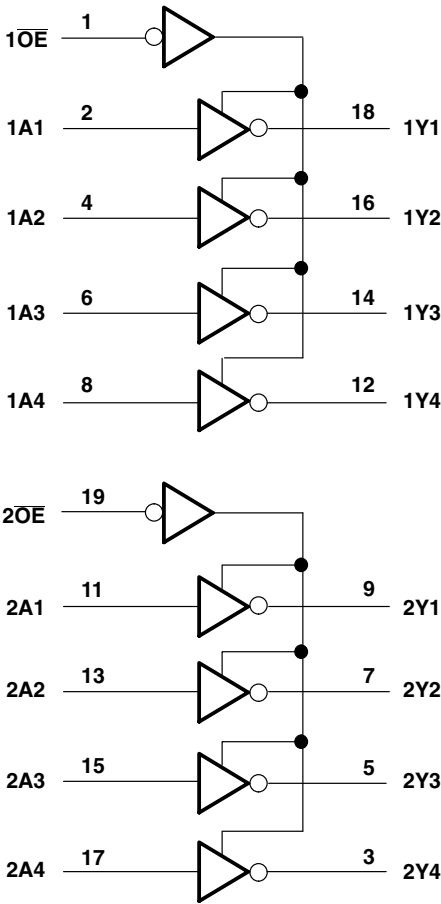
SN54BCT2240, SN74BCT2240
OCTAL BUFFERS AND LINE/MOS DRIVERS
WITH 3-STATE OUTPUTS

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FUNCTION TABLE
(each buffer)

INPUTS		OUTPUT Y
OE	A	
L	H	L
L	L	H
H	X	Z

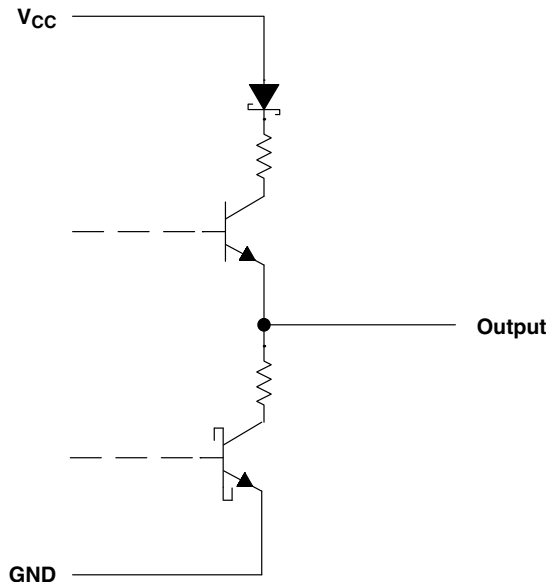
logic diagram (positive logic)



SN54BCT2240, SN74BCT2240 OCTAL BUFFERS AND LINE/MOS DRIVERS WITH 3-STATE OUTPUTS

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schematic of Y outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the disabled or power-off state, V_O	–0.5 V to 5.5 V
Voltage range applied to any output in the high state, V_O	–0.5 V to V_{CC}
Input clamp current, I_{IK}	–30 mA
Current into any output in the low state	24 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DB package	70°C/W
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.



SN54BCT2240, SN74BCT2240

OCTAL BUFFERS AND LINE/MOS DRIVERS

WITH 3-STATE OUTPUTS

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recommended operating conditions (see Note 3)

		SN54BCT2240			SN74BCT2240			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{IK}	Input clamp current			–18			–18	mA
I_{OH}	High-level output current			–12			–12	mA
I_{OL}	Low-level output current			12			12	mA
T_A	Operating free-air temperature	–55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		SN54BCT2240			SN74BCT2240			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V _{IK}	V _{CC} = 4.5 V, I _I = –18 mA		–1.2			–1.2			V
V _{OH}	V _{CC} = 4.5 V	I _{OH} = –1 mA	2.4	3.3		2.4	3.3		V
		I _{OH} = –12 mA	2	3.2		2	3.2		
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 1 mA		0.15	0.5		0.15	0.5	V
		I _{OL} = 12 mA		0.35	0.8		0.35	0.8	
I _I	V _{CC} = 5.5 V, V _I = 7 V		0.1			0.1			mA
I _{IH}	V _{CC} = 5.5 V, V _I = 2.7 V		20			20			μA
I _{IL}	V _{CC} = 5.5 V, V _I = 0.5 V		–1			–1			mA
I _{OZH}	V _{CC} = 5.5 V, V _O = 2.7 V		50			50			μA
I _{OZL}	V _{CC} = 5.5 V, V _O = 0.5 V		–50			–50			μA
I _{OS} ‡	V _{CC} = 5.5 V, V _O = 0		–100		–225	–100		–225	mA
I _{CCH}	V _{CC} = 5.5 V, Outputs open			19	32		19	32	mA
I _{CCL}	V _{CC} = 5.5 V, Outputs open			46	76		46	76	mA
I _{CCZ}	V _{CC} = 5.5 V, Outputs open			6	8		6	8	mA

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$			SN54BCT2240		SN74BCT2240		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	0.5	3.4	4.8	0.5	6.3	0.5	5.7	ns
t_{PHL}			0.5	2.8	4	0.5	4.6	0.5	4.4	
t_{PZH}	$\overline{OE}$	Y	2.6	6.2	8.2	2.6	10.1	2.6	9.3	ns
t_{PZL}			4.3	8.8	10.9	4.3	12.9	4.3	12.4	
t_{PHZ}	$\overline{OE}$	Y	2	5.3	7.1	2	9.2	2	8.7	ns
t_{PLZ}			2.2	6.7	8.5	2.2	12.2	2.2	10.6	

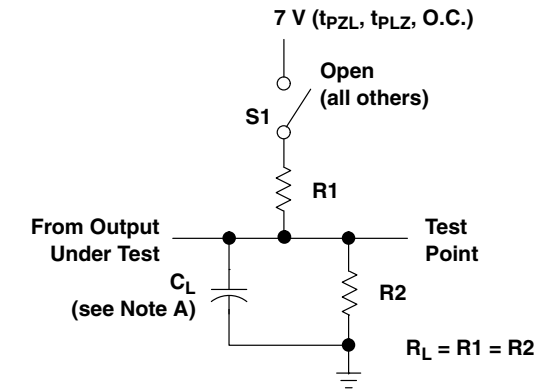


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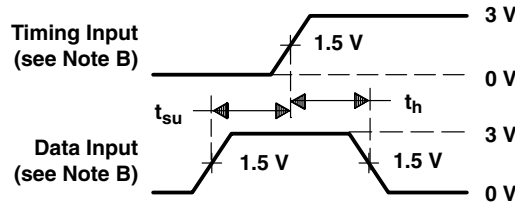
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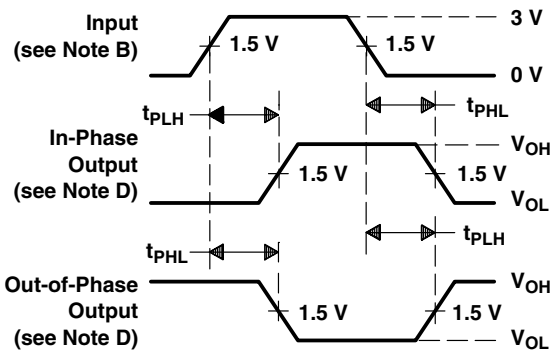
PARAMETER MEASUREMENT INFORMATION



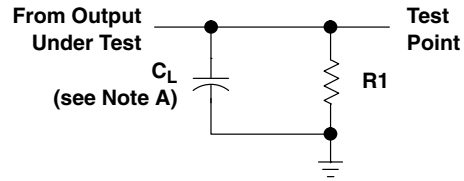
LOAD CIRCUIT FOR
3-STATE AND OPEN-COLLECTOR OUTPUTS



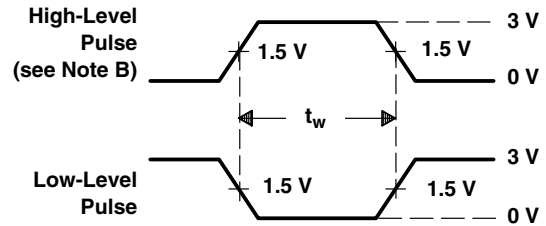
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



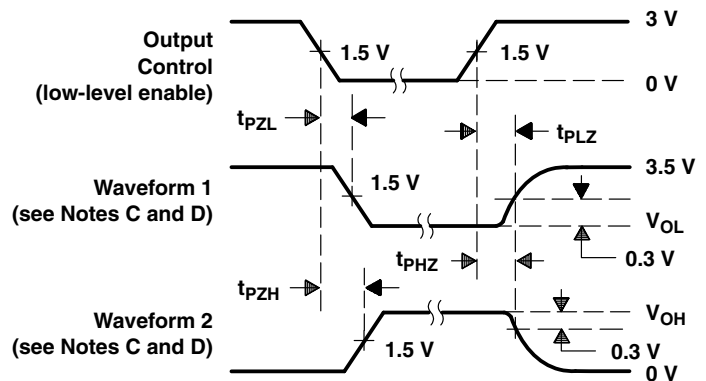
VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES (see Note D)



LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

- NOTES:
- C_L includes probe and jig capacitance.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $t_r = t_f \leq 2.5$ ns, duty cycle = 50%.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - The outputs are measured one at a time with one transition per measurement.
 - When measuring propagation delay times of 3-state outputs, switch S1 is open.
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9093901M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9093901MRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
5962-9093901MSA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
SN74BCT2240DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74BCT2240N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74BCT2240NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54BCT2240FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54BCT2240J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
SNJ54BCT2240W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

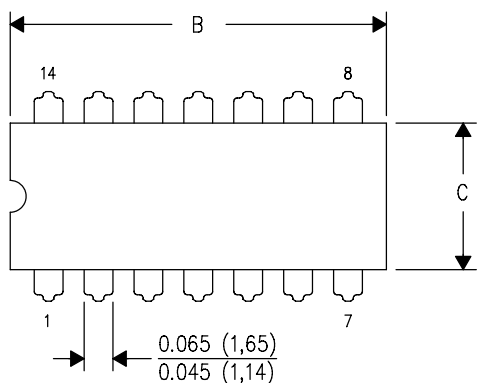
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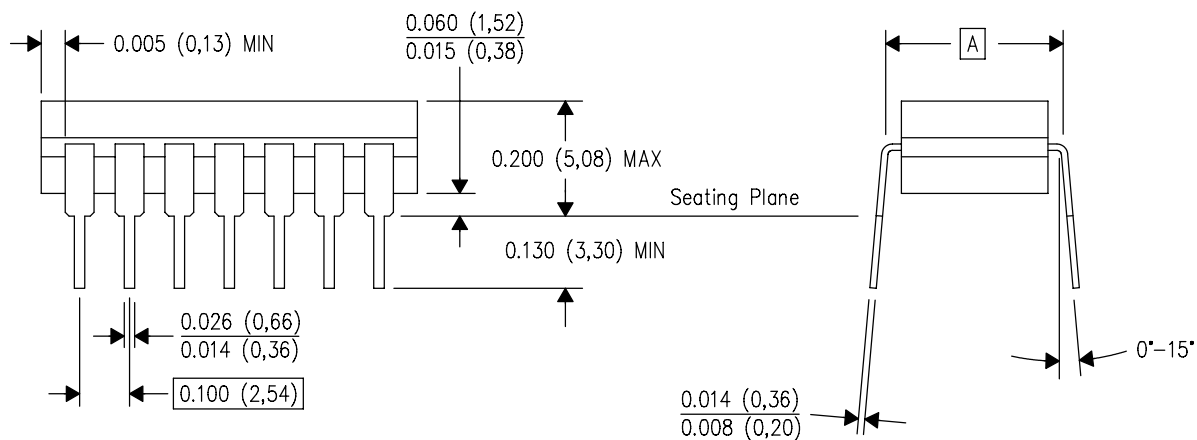
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

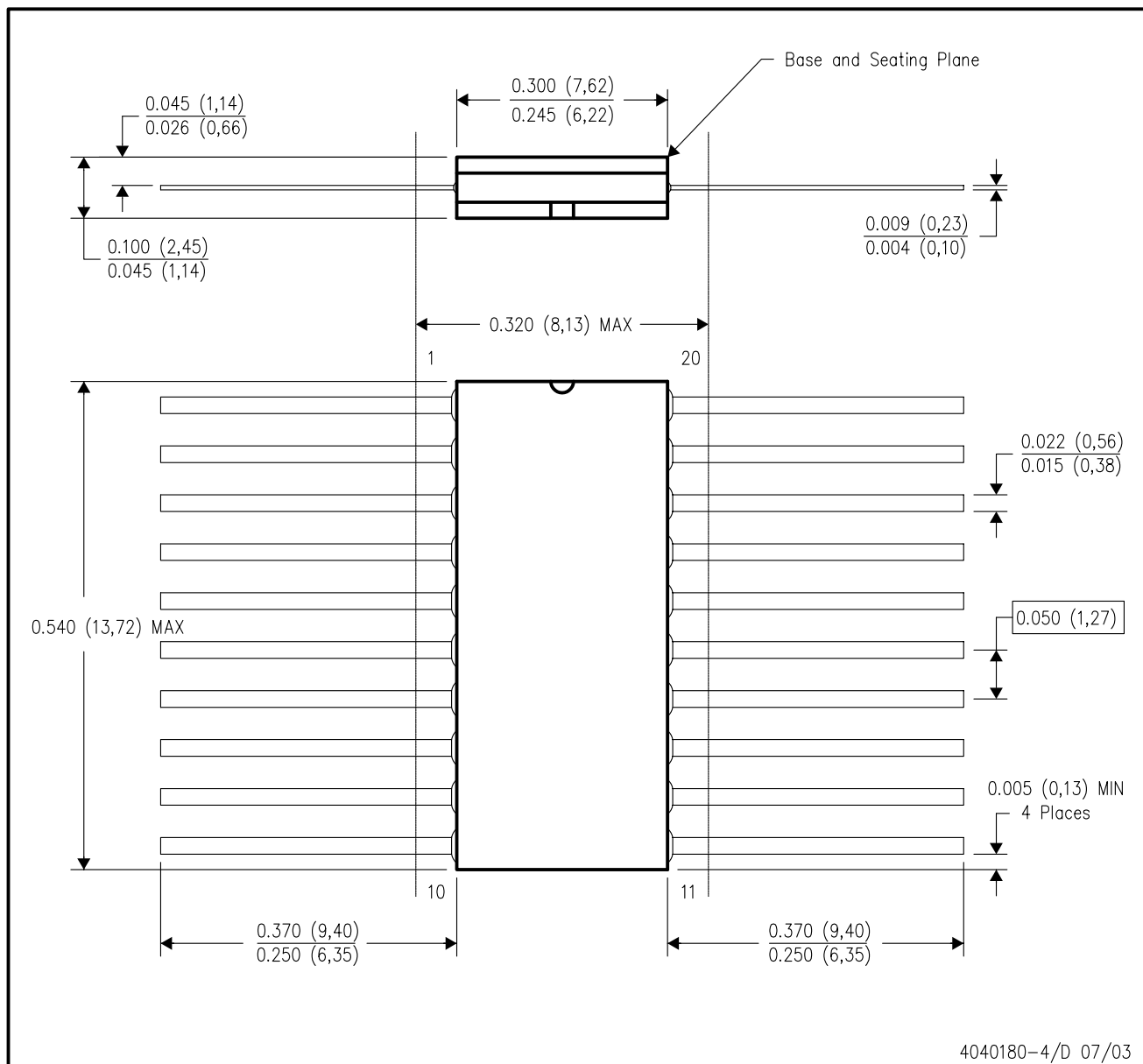


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- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK

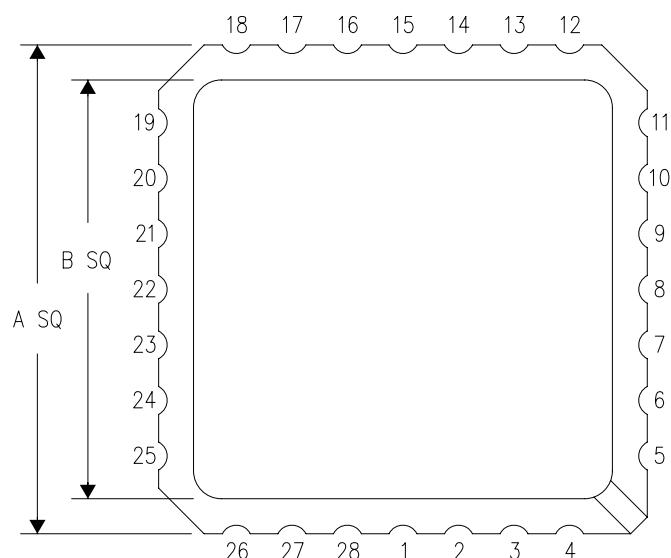


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within Mil-Std 1835 GDFP2-F20

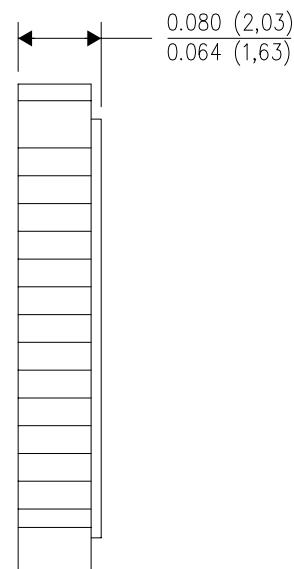
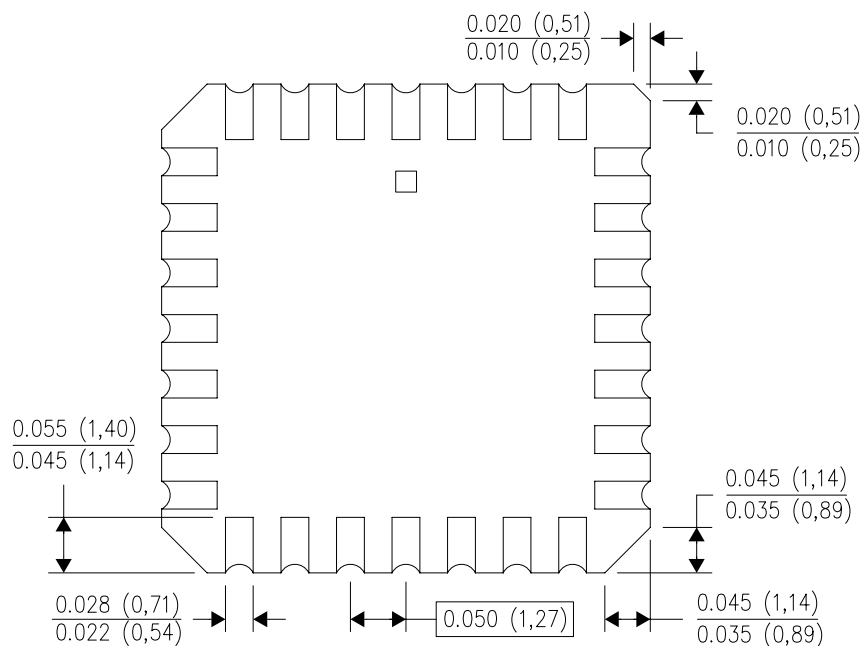
FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



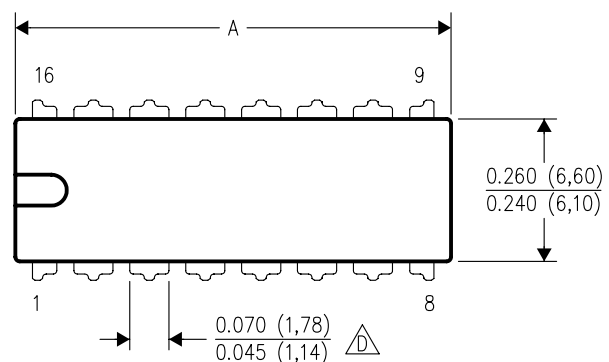
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- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

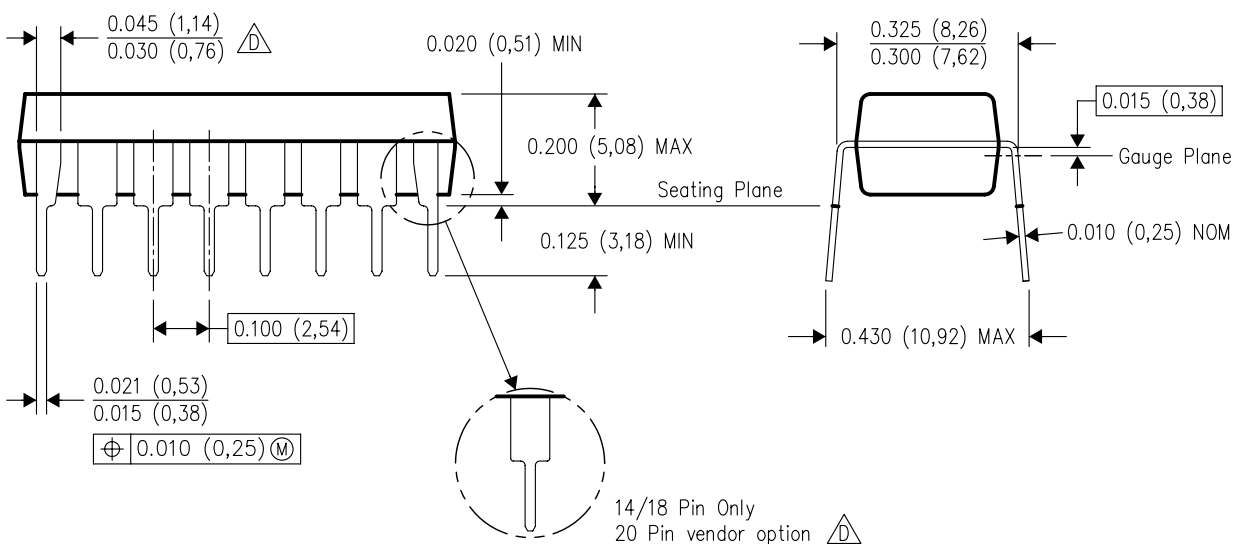
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



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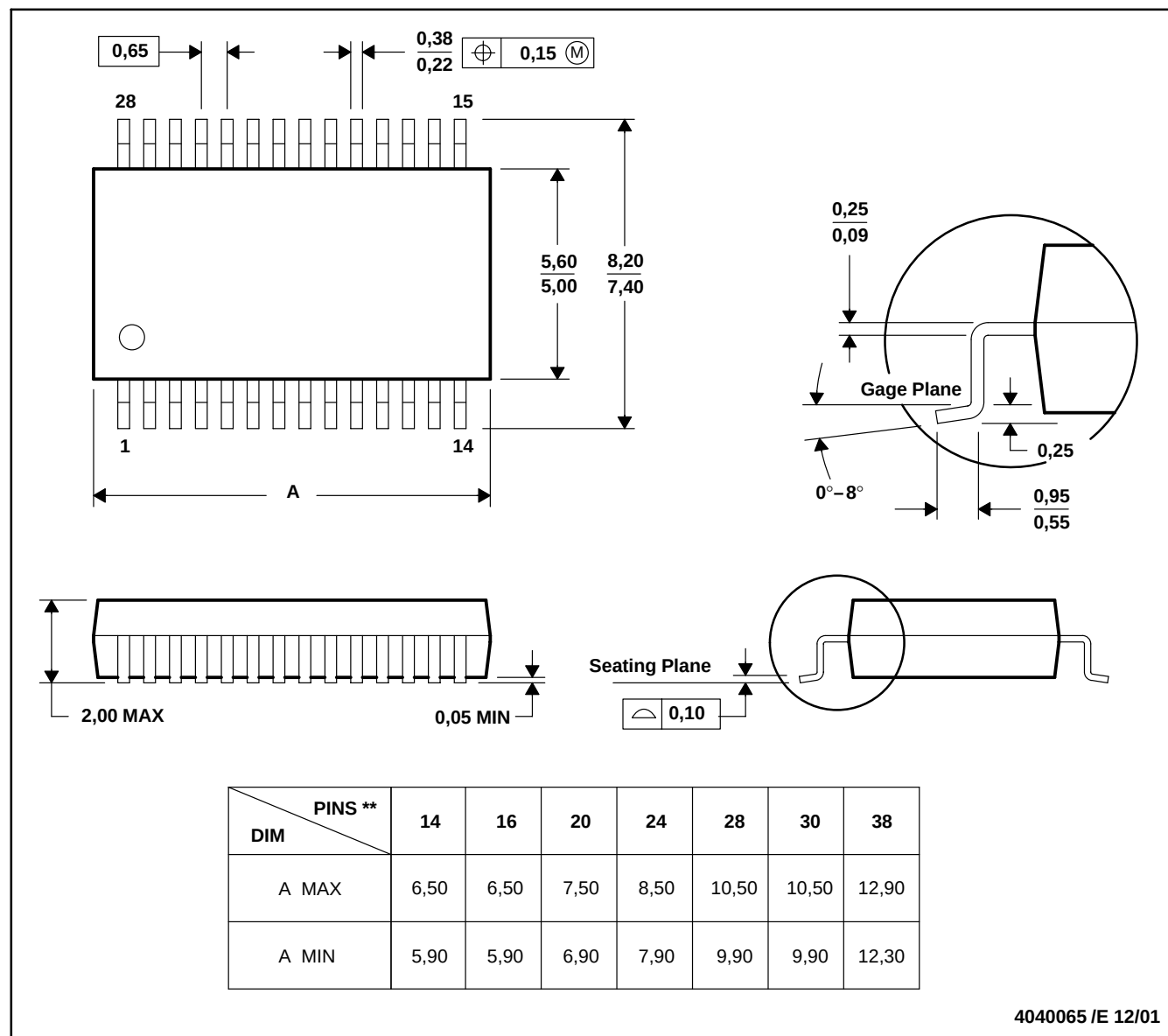
NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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